

20-3038 LOW DENSITY EPOXY SYNTACTIC FOAM

DESCRIPTION:

20-3038 is a light weight epoxy for potting, casting, and encapsulating electronic components and assemblies.

FEATURES:

- Chemical, solvent and moisture resistance
- Excellent electrical insulation properties
- Outstanding thermal shock and impact resistance
- Excellent adhesion

TYPICAL SPECIFICATIONS:

Viscosity @25°C cps, epoxy	10,000
Viscosity @25°C cps, hardener	10,000
Viscosity @25°C cps, mixed	10,000
Specific Gravity, 25°C	.85
Hardness, Shore D	75
Pot life, 100 gram mass at 25°C, minutes	20-25
Standard color	Grey
Mix ratio (epoxy:hardener)	
by weight	100:30

by weight 100:30 by volume 100:29.5

NOTE: This product is suitable for small to medium size potting applications. Avoid large potting applications due to the heat that is generated in large mass sizes.

INSTRUCTIONS FOR USE:

- 1. By weight, mix 30 parts 20-3038C to 100 parts 20-3038R.
- 2. Since this product contains low density fillers that will separate during storage, remix components prior to each use.

IMPORTANT:

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